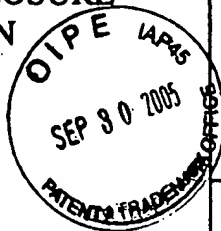
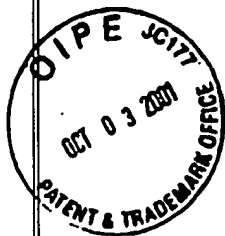


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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
J	4,796,194	01/03/89	Atherton			08/20/86
	5,089,970	02/18/92	Lee et al.			10/05/89
	5,108,570	04/28/92	Wang			03/30/90
	5,236,868	08/17/93	Nulman			04/20/90
	5,260,868	11/09/93	Gupta et al.			10/15/91
	5,295,242	03/15/94	Mashruwala et al.			11/02/90
	5,309,221	05/03/94	Fischer et al.			12/31/91
	5,367,624	11/22/94	Cooper			06/11/93
	5,398,336	03/14/95	Tantry et al.			06/16/93
	5,402,367	03/28/95	Sullivan et al.			07/19/93
A	5,408,405	04/18/95	Mozumder et al.			09/20/93
	5,410,473	04/25/95	Kaneko et al.			12/16/92
	5,490,097	02/06/96	Swenson et al.			08/06/93
	5,629,216	05/13/97	Wijaranakula et al.			02/27/96

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
B	HEI 1-283934	11/15/89	Japan			X	
	HEI 8-149583	06/07/96	Japan			X	
	HEI 9-34535	02/07/97	Japan			X	
	EP 0877308	11/11/98	Europe			X	
	HEI 11-67853	03/09/99	Japan			X	

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Dishon, G., D. Eylon, M. Finarov, and A. Shulman. "Dielectric CMP Advanced Process Control Based on Integrated Monitoring." Ltd. Rehoveth, Israel: Nova Measuring Instruments.

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①	5,661,669	08/26/97	Mozumder et al.			06/07/95
	5,698,989	12/16/97	Nulman			09/13/96
	5,719,495	02/17/98	Moslehi			06/05/96
	5,740,429	04/14/98	Wang et al.			07/07/95
	5,751,582	05/12/98	Saxena et al.			09/24/96
	5,754,297	05/19/98	Nulman			04/14/97
	5,764,543	06/09/98	Kennedy			06/16/95
	5,808,303	09/15/98	Schlagheck et al.			01/29/97
	5,883,437	03/16/99	Maruyama et al.			12/28/95
	5,910,011	06/08/99	Cruse			05/12/97
	6,054,379	04/25/00	Yau et al.			02/11/98

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	Zorich, Robert. 1991. <i>Handbook of Quality Integrated Circuit Manufacturing</i> . pp. 464-498 San Diego, California: Academic Press, Inc.
	Rampalli, Prasad, Arakere Ramesh, and Nimish Shah. 1991. CEPT—A Computer-Aided Manufacturing Application for Managing Equipment Reliability and Availability in the Semiconductor Industry. New York, New York: IEEE.
	Moyne, James R., Nauman Chaudhry, and Roland Telfeyan. 1995. "Adaptive Extensions to a Multi-Branch Run-to-Run Controller for Plasma Etching." <i>Journal of Vacuum Science and Technology</i> . Ann Arbor, Michigan: University of Michigan Display Technology Manufacturing Center.
	Moyne, James, Roland Telfeyan, Arnon Hurwitz, and John Taylor. August 1995. "A Process-Independent Run-to-Run Controller and Its Application to Chemical-Mechanical Planarization." <i>SEMI/IEEE Advanced Semiconductor Manufacturing Conference and Workshop</i> . Ann Arbor, Michigan: The University of Michigan, Electrical Engineering & Computer Science Center for Display Technology & Manufacturing.

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J	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium		
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System		
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder		
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers		

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	Dishon, G., M. Finarov, R. Kipper, J.W. Curry, T. Schraub, D. Trojan, 4 th Stambaugh, Y. Li and J. Ben-Jacob. February 1996. "On-Line Integrated Metrology for CMP Processing." Santa Clara, California: VMIC Speciality Conferences, 1 st International CMP Planarization Conference.
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J	Van Zant, Peter. 1997. <i>Microchip Fabrication: A Practical Guide to Semiconductor Processing</i> . Third Edition, pp. 472-478. New York, New York: McGraw-Hill.
	Campbell, W. Jarrett, and Anthony J. Toprac. February 11-12, 1998. "Run-to-Run Control in Microelectronics Manufacturing." Advanced Micro Devices, TWMCC.
J	Consilium. August 1998. <i>Quality Management Component: QMC™ and QMC-Link™ Overview</i> . Mountain View, California: Consilium, Inc.
	Consilium. 1998. <i>FAB300™</i> . Mountain View, California: Consilium, Inc.
	Khan, Kareemullah, Victor Solakhan, Anthony Ricci, Tier Gu, and James Moyne. 1998. "Run-to-Run Control of ITO Deposition Process." Ann Arbor, Michigan.
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EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS
B	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service		
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems		
A	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide		



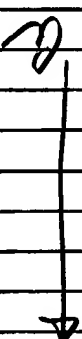
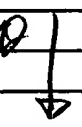


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B	SEMI. July 1998. <i>New Standard: Provisional Specification for CIM Framework Domain Architecture</i> . Mountain View, California: SEMI Standards. SEMI Draft Doc. 2817.
y	Consilium. July 1999. "Increasing Overall Equipment Effectiveness (OEE) in Fab Manufacturing by Implementing Consilium's Next-Generation Manufacturing Execution System - MES II." Semiconductor Fabtech Edition 10.
y	Consilium Corporate Brochure. October 1999. www.consilium.com
y	Consilium. January 1999. "FAB300™: Consilium's Next Generation MES Solution of Software and Services which Control and Automate Real-Time FAB Operations." www.consilium.com/products/fab300_page.htm#FAB300 Introduction
y	Consilium. November 1999. <i>FAB300™ Update</i> .
y	SEMI. 2000. "Provisional Specification for CIM Framework Scheduling Component." San Jose, California. SEMI E105-1000.
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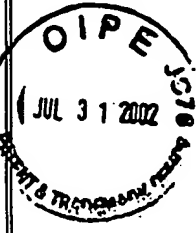


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  (PTO-1449)				APPLICANT Huey-Shin YUAN et al.		RECEIVED AUG 02 2002 GROUP 3600	
				FILING DATE March 20, 2001		GROUP 2163	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO./ PUBLICATION NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	5,220,517	06/15/93	Sierk et al.			08/31/90	
	5,329,463	07/12/94	Sierk et al.			01/13/93	
	5,495,417	02/27/96	Fuduka et al.			03/16/93	
	5,497,316	03/05/96	Sierk et al.			04/04/95	
	5,503,707	04/02/96	Maung et al.			09/22/93	
	5,508,947	04/16/96	Sierk et al.			05/13/94	
	5,657,254	08/12/97	Sierk et al.			04/15/96	
	5,694,325	12/02/97	Fukuda et al.			11/22/95	
	5,838,595	11/17/98	Sullivan et al.			11/25/96	
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	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
	2,194,855	08/29/91	Canada			X	
	05-151231	06/18/93	Japan				X
	05-216896	08/27/93	Japan				X
	05-266029	10/15/93	Japan				X
	06-110894	04/22/94	Japan				X
	06-176994	06/24/94	Japan				X
	06-252236	09/09/94	Japan				X
	06-260380	09/16/94	Japan				X
	1072967A3	11/21/01	Europe			X	
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EXAMINER 				DATE CONSIDERED 10/5/05			

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FOREIGN PATENT DOCUMENTS							
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/	Zhou, Zhen-Hong and Rafael Reif. August 1995. "Epi-Film Thickness Measurements Using Emission Fourier Transform Infrared Spectroscopy—Part II: Real-Time <i>in Situ</i> Process Monitoring and Control." IEEE Transactions on Semiconductor Manufacturing, Vol. 8, No. 3.						
/	Telfeyan, Roland, James Moyne, Nauman Chaudhry, James Pugmire, Scott Shellman, Duane Boning, William Moyne, Arnon Hurwitz, and John Taylor. October 1995. "A Multi-Level Approach to the Control of a Chemical-Mechanical Planarization Process." Minneapolis, Minnesota: 42 nd National Symposium of the American Vacuum Society.						
/	Chang, E., B. Stine, T. Maung, R. Divecha, D. Boning, J. Chung, K. Chang, G. Ray, D. Bradbury, O. S. Nakagawa, S. Oh, and D. Bartelink. December 1995. "Using a Statistical Metrology Framework to Identify Systematic and Random Sources of Die- and Wafer-level ILD Thickness Variation in CMP Processes." Washington, D.C.: International Electron Devices Meeting.						
/	Smith, Taber, Duane Boning, James Moyne, Arnon Hurwitz, and John Curry. June 1996. "Compensating for CMP Pad Wear Using Run by Run Feedback Control." Santa Clara, California: VLSI Multilevel Interconnect Conference.						
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						Yes	No
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Boning, Duane, William Moyne, Taber Smith, James Moyne, Roland Telfeyan, Arnon Hurwitz, Scott Shellman, and John Taylor. October 1996. "Run by Run Control of Chemical-Mechanical Polishing." <i>IEEE Trans. CPMT (C)</i> , Vol. 19, No. 4, pp. 307-314.							
Edgar, Thomas F., Stephanie W. Butler, Jarrett Campbell, Carlos Pfeiffer, Chris Bode, Sung Bo Hwang, and K.S. Balakrishnan. May 1998. "Automatic Control in Microelectronics Manufacturing: Practices, Challenges, and Possibilities." <i>Automatica</i> , Vol. 36, pp. 1567-1603, 2000.							
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Moyne, James. October 1999. "Advancements in CMP Process Automation and Control." Hawaii: (Invited paper and presentation to) Third International Symposium on Chemical Mechanical Polishing in IC Device Manufacturing: 196 th Meeting of the Electrochemical Society.							
Lee, Brian, Duane S. Boning, Winthrop Baylies, Noel Poduje, Pat Hester, Yong Xia, John Valley, Chris Koliopoulos, Dale Hetherington, Hongliang Sun, and Michael Lacy. April 2001. "Wafer Nanotopography Effects on CMP: Experimental Validation of Modeling Methods." San Francisco, California: Materials Research Society Spring Meeting.							
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	4,967,381	10/30/90	Lane et al.			07/06/89
	5,208,765	05/04/93	Turnbull			07/20/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
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	5,525,808	06/11/96	Irie et al.			12/20/94
	5,586,039	12/17/96	Hirsch et al.			02/27/95
	5,603,707	02/18/97	Trombetta et al.			11/28/95
	5,664,987	09/09/97	Renteln			09/04/96
	5,812,407	09/22/98	Sato et al.			08/12/97
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A/g	61-171147	08/01/86	Japan				X
	6-184434	07/05/94	Japan				X
	0 621 522 A2	10/26/94	Europe			X	
	8-50161	02/20/96	Japan				X
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	February 1984. "Method and Apparatus of in Situ Measurement and Overlay Error Analysis for Correcting Step and Repeat Lithographic Cameras." <i>IBM Technical Disclosure Bulletin</i> , pp. 4855-4859.
A	October 1984. "Method to Characterize the Stability of a Step and Repeat Lithographic System." <i>IBM Technical Disclosure Bulletin</i> , pp. 2857-2860.

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J1	5,859,964	01/12/99	Wang et al.			10/25/96
	5,863,807	01/26/99	Jang et al.			03/15/96
	5,870,306	02/09/99	Harada			06/13/97
	5,903,455	05/11/99	Sharpe, Jr. et al.			12/12/96
	5,916,016	06/29/99	Bothra			10/23/97
	5,923,553	07/13/99	Yi			10/05/96
	5,930,138	07/27/99	Lin et al.			09/10/97
	5,940,300	08/17/99	Ozaki			05/08/97
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96
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	5,982,920	11/09/99	Tobin, Jr. et al.			01/08/97
	6,041,270	03/21/00	Steffan et al.			12/05/97
	6,078,845	06/20/00	Friedman			11/25/96
	6,112,130	08/29/00	Fukuda et al.			10/01/97
	6,148,246	11/14/00	Kawazome			06/10/98

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J1	0 747 795 A2	12/11/96	Europe			X	
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	0 895 145 A1	02/03/99	Europe			X	
	11-126816	05/11/99	Japan				X

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J1	Schmid, Hans Albrecht. 1995. "Creating the Architecture of a Manufacturing Framework by Design Patterns." Austin, Texas: OOPSLA.
J1	Baliga, John. July 1999. "Advanced Process Control: Soon to be a Must." Cahners Semiconductor International. www.semiconductor.net/semiconductor/issues/issues/1999/jul99/docs/feature1.asp

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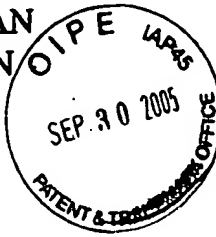
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	6,178,390	01/23/01	Jun			09/08/98
	6,185,324	02/06/01	Ishihara et al.			01/31/95
	6,192,291	02/20/01	Kwon			10/08/98
	6,197,604	03/06/01	Miller et al.			10/01/98
	6,211,094	04/03/01	Jun et al.			08/23/99
	6,226,792	05/01/01	Goiffon et al.			10/14/98
	6,230,069	05/08/01	Campbell et al.			06/26/98
	6,236,903	05/22/01	Kim et al.			09/25/98
<i>JS</i>	6,240,330	05/29/01	Kurtzberg et al.			05/28/97

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	11-135601	05/21/99	Japan				X
<i>JS</i>	WO 00/05759	02/03/00	WO			X	
	WO 00/35063	06/15/00	WO			X	

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<i>JS</i>	July 5, 2001. "Motorola and Advanced Micro Devices Buy ObjectSpace Catalyst Advanced Process Control Product for Five Wafer Fabs." Semiconductor FABTECH. www.semiconductorfabtech.com/industry.news/9907/20.07.shtml
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<i>JS</i>	Sonderman, Thomas. 2002. "APC as a Competitive Manufacturing Technology: AMD's Vision for 300mm ² AEC/APC.

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Scott Jacob

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10/5/05

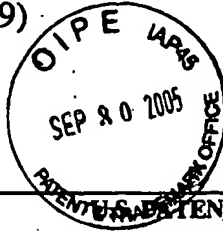
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**INFORMATION DISCLOSURE
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ATTY. DOCKET NO.
5957/Consilium/MBE

SERIAL NO.
09/811,667

APPLICANT
Huey-Shin YUAN et al.

FILING DATE
March 20, 2001

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M	6,240,331	05/29/01	Yun			08/18/98
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M	WO 00/79355 A1	12/28/00	WO			X	
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						Yes	No
	2 347 885 A	09/20/00	GB			X	
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<i>19</i>	5,270,222	12/14/93	Moslehi			12/31/90
	5,375,064	12/20/94	Bollinger			12/02/93
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EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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<i>19</i>	WO 95/34866	12/21/95	WO			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
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g ↓	5,889,991	03/30/99	Consolatti et al.			12/06/96
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b ↓	WO 01/52055 A3	07/19/01	WO			X	
	WO 01/57823 A2	08/09/01	WO			X	
	EP 1 182 526 A2	02/27/02	Europe			X	
	WO 02/17150 A1	02/28/02	WO			X	
	WO 02/33737 A2	04/25/02	WO			X	

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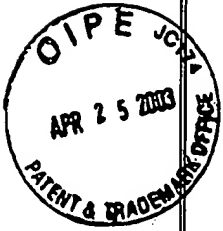
	Chemali, Chadi El, James Moyne, Kareemullah Khan, Rock Nadeau, Paul Smith, John Colt, Jonathan Chapple-Sokol, and Tarun Parikh. July/August 2000. "Multizone Uniformity Control of a Chemical Mechanical Polishing Process Utilizing a Pre- and Postmeasurement Strategy." J. Vac. Sci. Technol. A, Vol. 18(4). pp. 1287-1296. American Vacuum Society.
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EXAMINER	DATE CONSIDERED
<i>Scott J. Smith</i>	<i>10/5/05</i>

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>[initials]</i>	3,205,485	09/07/65	Noltingk			10/21/60
<i>[initials]</i>	3,229,198	01/11/66	Libby			09/28/62
<i>[initials]</i>	4,000,458	12/28/76	Miller et al.			08/21/75
<i>[initials]</i>	4,302,721	11/24/81	Urbanek et al.			05/15/79
<i>[initials]</i>	4,750,141	06/07/88	Judell et al.			11/26/85
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<i>[initials]</i>	5,283,141	02/01/94	Yoon et al.			03/05/92
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<i>H</i>	6,159,075	12/12/00	Zhang			10/13/99
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<i>D</i>	6,320,655	11/20/01	Matsushita et al.			03/15/00

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<i>h</i>	2001/0042690	11/22/01	Talieh			12/14/00
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	6,334,807	01/01/02	Lebel et al.			04/30/99
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<i>h</i>	2002/0127950	09/12/02	Hirose et al.			03/08/01
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	2003/0020928	01/30/03	Ritzdorf et al.			07/09/01
<i>Y</i>	6,517,413	02/11/03	Hu et al.			10/25/00

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						Yes	No
<i>J</i>	61-66104	04/04/86	Japan			X	
	3-202710	09/04/91	Japan			X	
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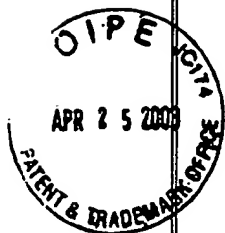
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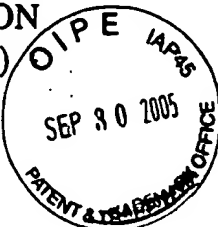
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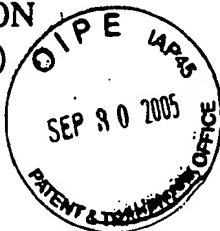
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EXAMINER <i>Scott J. Jant</i>	DATE CONSIDERED <i>10/5/05</i>	RECEIVED OCT 14 2003
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GROUP 3600



INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)

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ATTY. DOCKET NO. 005957 USA/Consilium/Consilium	SERIAL NO. 09/811,667
APPLICANT Huey-Shin YUAN et al.	
FILING DATE March 20, 2001	GROUP 2163

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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J	WO 01/11679	02/15/01	WIPO			X	
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EXAMINER <i>Andrzej Jankowski</i>	DATE CONSIDERED <i>10/5/05</i>
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APPLICANT
Huey-Shin YUAN et al.





FILING DATE
March 20, 2001

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				FILING DATE March 20, 2001		GROUP 2163		
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<div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;">  </div> <div style="text-align: center;">  </div> </div>				APPLICANT Huey-Shin YUAN et al.		GROUP 36	
				FILING DATE March 20, 2001			
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
15	0 397 924 A1	11/22/90	Europe			X	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
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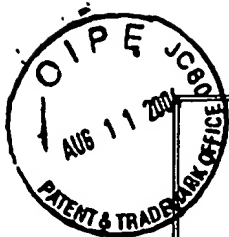
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Consilium/ConsiliumSERIAL NO.
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Huey-Shin YUAN et al.FILING DATE
March 20, 2001GROUP
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EXAMINER <i>And Jank</i>			DATE CONSIDERED <i>10/5/05</i>			

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SHEET 2 OF 4

INFORMATION DISCLOSURE
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APPLICATION (PTO-1449)ATTY. DOCKET NO.
005957 USA/
Consilium/ConsiliumSERIAL NO.
09/811,667APPLICANT
Huey-Shin YUAN et al.FILING DATE
March 20, 2001GROUP
2163

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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Andrew J. Smith

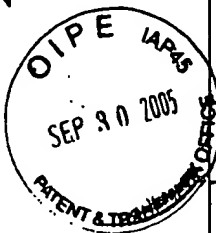
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March 20, 2001GROUP
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FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
H ↓	EP 0 932 195 A1	07/28/99	EP			X	
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